

Data sheet

Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND
HIGH POWER · ANTI SURGE ANTI-SULFRATION

Style: RPGW16,20,32,35

AEC-Q200 qualified

RoHS COMPLIANCE ITEM
Halogen and Antimony Free

- Note:
- Stock conditions
Temperature: +5°C ~ +35°C
Relative humidity: 25% ~ 75%
The period of guarantee: Within 2 year from shipment by the company.
Solderability shall be satisfied.
 - Product specification contained in this data sheet
are subject to change at any time without notice
 - If you have any questions or a Purchasing Specification for any quality
Agreement is necessary, please contact our sales staff.



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1. Scope

1.1 This data sheet covers the detail requirements for fixed thick film chip resistors; rectangular type & high power · anti surge anti sulfuration, style of RPGW16,20,32,35.

1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014

IEC60115-1: 2008, IEC60115-8: 2009, IEC60115-8-1: 2014

EIAJ RC-2134C-2010

2. Classification

Type designation shall be the following form.

(Example)	RPGW	32	K	123	J	TP
	1	2	3	4	5	6
	Style					

1 Fixed thick film chip resistors; rectangular type & high power · anti surge anti-sulfuration.

2 Rated dissipation and / or dimension

3 Temperature coefficient of resistance

K	$\pm 100 \times 10^{-6} / ^\circ\text{C}$
-(Dash)	Standard

 Style

4 Rated resistance

123	E24 Series, 3 digit, Ex. 123--> 12k Ω ,
1000	E96 Series, 4 digit, Ex. 1000-->100 Ω 1022--> 10.2k Ω

5 Tolerance on rated resistance

D	$\pm 0.5\%$
F	$\pm 1\%$
J	$\pm 5\%$

6 Packaging form

B	Bulk (loose package)
TP	Paper taping
TE	Embossed taping

3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1

Style	Rated dissipation (W)	Temperature coefficient of resistance ($10^{-6} / ^\circ\text{C}$)		Rated resistance range (Ω)	Preferred number series for resistors	Tolerance on rated resistance
RPGW16	0.33	K	± 100	10~1M	E24, 96	D($\pm 0.5\%$), F($\pm 1\%$)
		Standard	± 200	1.0~9.76		
		K	± 100	10~1M	E24	J($\pm 5\%$)
		Standard	± 200	1.0~9.1		
RPGW20	0.5	K	± 100	10~1M	E24, 96	D($\pm 0.5\%$), F($\pm 1\%$)
		Standard	± 200	1.0~9.76		
		K	± 100	10~1M	E24	J($\pm 5\%$)
		Standard	± 200	1.0~9.1		
RPGW32	0.66	K	± 100	10~1M	E24, 96	D($\pm 0.5\%$), F($\pm 1\%$)
		Standard	± 200	1.0~9.76		
		K	± 100	10~1M	E24	J($\pm 5\%$)
		Standard	± 200	1.0~9.1		
RPGW35	0.75	K	± 100	10~1M	E24, 96	D($\pm 0.5\%$), F($\pm 1\%$)
		Standard	± 200	1.0~9.76		
		K	± 100	10~1M	E24	J($\pm 5\%$)
		Standard	± 200	1.0~9.1		

Style	Limiting element voltage (V)	Isolation voltage (V)	Category temperature range(°C)
RPGW16	150	150	-55~+155
RPGW20	200	500	
RPGW32			
RPGW35			

3.2 Climatic category

55/155/56

Lower category temperature

- 55 $^\circ\text{C}$

Upper category temperature

+155 $^\circ\text{C}$

Duration of the damp heat, steady state test

56days

3.3 Stability class

5%

Limits for change of resistance:

-for long-term tests $\pm(5\%+0.1\Omega)$

-for short-term tests $\pm(1\%+0.05\Omega)$

3.4 Derating

The derated values of dissipation at temperature in excess of 70 $^\circ\text{C}$ shall be as indicated by the following curve.

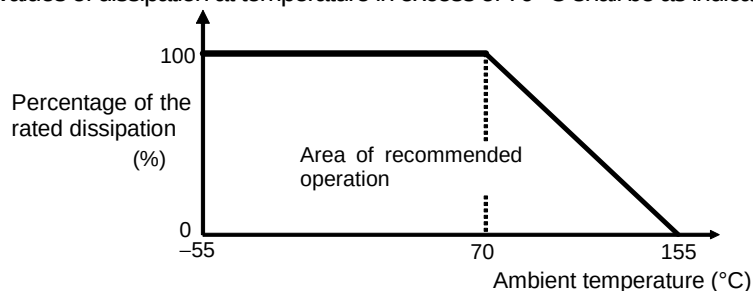


Figure-1 Derating curve

3.5 Rated voltage

d.c.or a.c.r.m.s.voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

$$E = \sqrt{P \cdot R}$$

E: Rated voltage (V)

P: Rated dissipation (W)

R: Rated resistance (Ω)

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
B	Bulk (loose package)		1,000 pcs.	RPGW16,20,32,35
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RPGW 16,20,32
TE	Embossed taping	8mm width, 4mm pitches	4,000 pcs.	RPGW 35

5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

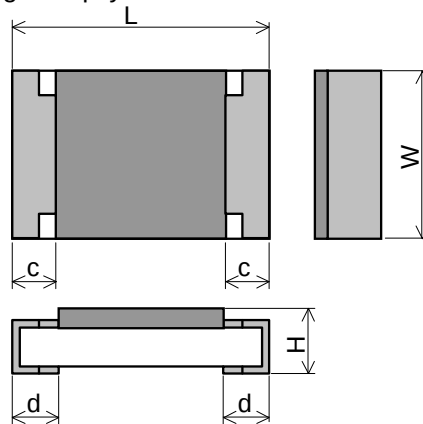


Figure-2

Table-3

Unit: mm

Style	L	W	H	c	d
RPGW16	1.6±0.1	0.8 ^{+0.15} _{-0.05}	0.45±0.10	0.3±0.2	0.3±0.1
RPGW20	2.0±0.1	1.25±0.10	0.55±0.10	0.3±0.2	0.4±0.2
RPGW32	3.1±0.1	1.6±0.15	0.55±0.10	0.4±0.25	0.5±0.25
RPGW35	3.1±0.15	2.5±0.15	0.55±0.15	0.4±0.25	0.5±0.25

5.2 Net weight (Reference)

Style	Net weight(mg)
RPGW16	2
RPGW20	5
RPGW32	9
RPGW35	16

6. Marking

The Rated resistance shall be marked in 3 digits (E24) or 4 digits (E96) and marked on over coat side.

- E24 series: 3 digits, E96 series: 4 digits

In case of the resistance value that E96 overlaps with E24, It is marked by either.

The Rated resistance of RPGW16 should not be marked in 4 digits(E96).

Marking example	Contents	Application
123	$12 \times 10^{-3} [\Omega] \rightarrow 12 [\text{k}\Omega]$	RPGW 16,20,32,35
2R2	2.2 $[\Omega]$	Less than 10Ω of RPGW 16,20,32,35
5623	$562 \times 10^3 [\Omega] \rightarrow 562 [\text{k}\Omega]$	RPGW 20,32,35
12R7	12.7 $[\Omega]$	RPGW 20,32,35

7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201-1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items	Condition of test (JIS C 5201-1)	Performance requirements
1	Visual examination	Sub-clause 4.4.1 Checked by visual examination.	As in 4.4.1 The marking shall be legible, as checked by visual examination.
2	Dimension Resistance	Sub-clause 4.4.2 Sub-clause 4.5	As specified in Table-3 of this specification. As in 4.5.2 The resistance value shall correspond with the rated resistance taking into account the specified tolerance.
3	Voltage proof	Sub-clause 4.7 Method: 4.6.1.4 Test voltage: Alternating voltage with a peak value of 1.42 times the insulation voltage. Duration: 60 s $\pm$ 5 s Insulation resistance Test voltage: Insulation voltage Duration: 1 min.	No breakdown or flash over $R \geq 1 \text{ G}\Omega$
4	Solderability	Sub-clause 4.17 Without ageing Flux: The resistors shall be immersed in a non-activated soldering flux for 2s. Bath temperature: 235 °C $\pm$ 5 °C Immersion time: 2 s $\pm$ 0.5 s	As in 4.17.4.5 The terminations shall be covered with a smooth and bright solder coating.

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Table-4(2)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
5	Mounting Overload (in the mounted state) Solvent resistance of the marking	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.13 The applied voltage shall be 2.5 times the rated voltage or twice the limiting element voltage, whichever is the less severe. Duration: 2 s Visual examination Resistance Sub-clause 4.30 Solvent: 2-propanol Solvent temperature: 23 °C ± 5 °C Method 1 Rubbing material: cotton wool Without recovery	No visible damage $\Delta R \leq \pm (1\%+0.05\Omega)$ Legible marking
6	Mounting Bound strength of the end face plating Final measurements	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.33 Bent value: 3 mm Resistance Sub-clause 4.33.6 Visual examination	$\Delta R \leq \pm (1\%+0.05\Omega)$ No visible damage
7	Resistance to soldering heat Component resistance solvent	Sub-clause 4.18 Solder temperature: 260 °C ± 5 °C Immersion time: 10 s ± 0.5 s Visual examination Resistance Sub-clause 4.29 Solvent: 2-propanol Solvent temperature: 23 °C ± 5 °C Method 2 Recovery: 48 h Visual examination Resistance	As in 4.18.3.4 No sign of damage such as cracks. $\Delta R \leq \pm (1\%+0.05\Omega)$ No visible damage $\Delta R \leq \pm (1\%+0.05\Omega)$

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Table-4(4)

No	Test items	Condition of test (JIS C 5201-1)	Performance requirements
11	Mounting Variation of resistance with temperature	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.8 -55 °C / +20 °C +20 °C / +155°C	As in Table-1
12	Mounting Damp heat, steady state	Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.24 Ambient temperature: 40 °C ± 2 °C Relative humidity : 93 $\pm$ ₃ % a) 1st group: without voltage applied. b) 2nd group: The d. c. voltage shall be applied continuously. The voltage shall be accordance with Sub-clause 4.24.2.1 b). without polarizing voltage [4.24.2.1, c)] Visual examination Resistance	No visible damage Legible marking $\Delta R \leq \pm (5\%+0.1\Omega)$
13	Dimensions (detail) Mounting Endurance at upper category temperature	Sub-clause 4.4.3 Sub-clause 4.31 Substrate material: Epoxide woven glass Sub-clause 4.25.3 Ambient temperature:155 °C ± 2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	As in Table-3 No visible damage $\Delta R \leq \pm (5\%+0.1\Omega)$
14	Humid Sulfur vapor test (FOS)	ASTM B809 Reagent: Sulfur (Saturated vapor) Test temp.: 60°C Relative humidity: 95%RH Test period: 1000h Resistance	$\Delta R \leq \pm (1\%+0.05\Omega)$

8. Taping

8.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010

8.2 Taping dimensions

8.2.1 Taping dimensions shall be in accordance with Figure-3 and Table-5.

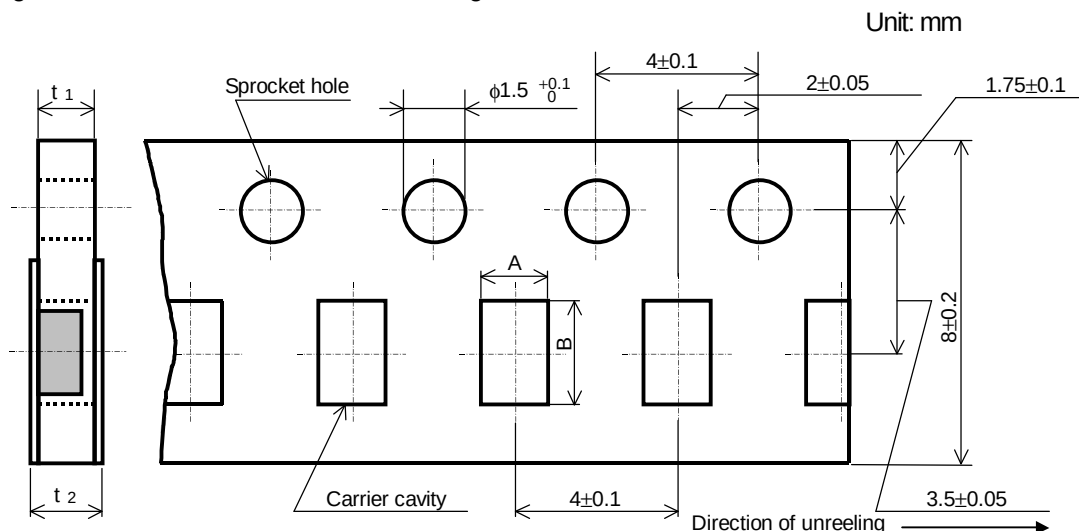


Figure-3

Table-5

Unit: mm

Style	A	B	t ₁	t ₂
RPGW16	1.15±0.15	1.9±0.2	0.6±0.1	0.8max.
RPGW20	1.65±0.15	2.5±0.2	0.8±0.1	1.0max.
RPGW32	2.00±0.15	3.6±0.2	0.8±0.1	1.0max.

8.2.2 Embossed taping dimensions shall be in accordance with Figure-4 and Table-6.

Unit: mm

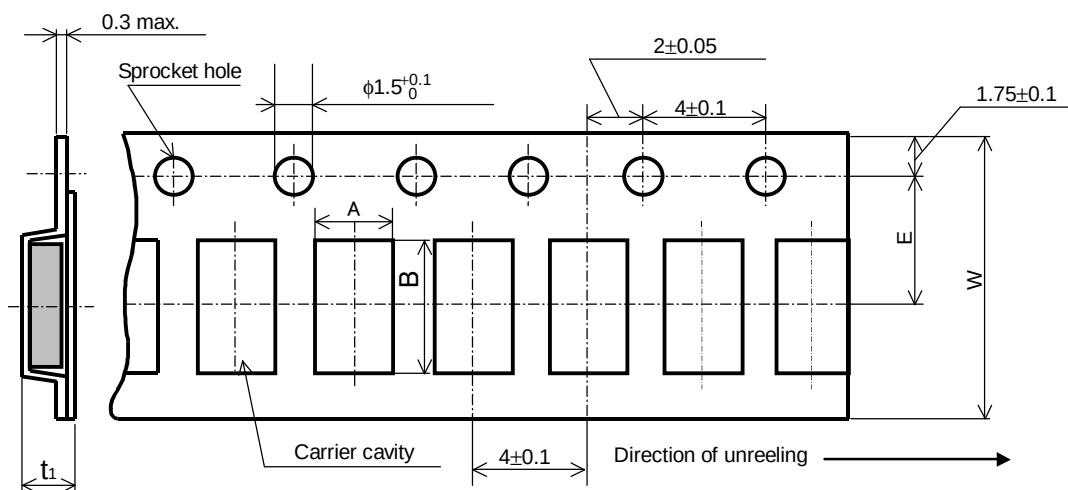


Figure-4

Table-6

Unit: mm

Style	A	B	W	E	t ₁
RPGW35	2.85±0.20	3.5±0.2	8.0±0.3	3.5±0.05	1.0±0.2

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches $\pm 0.2\text{mm}$.
- 5). The peel strength of the top cover tape shall be within 0.1N to 0.5N on the test method as shown in the following
RPGW16,20,32:Figure-4,RPGW35:Figure-5.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing.
The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.

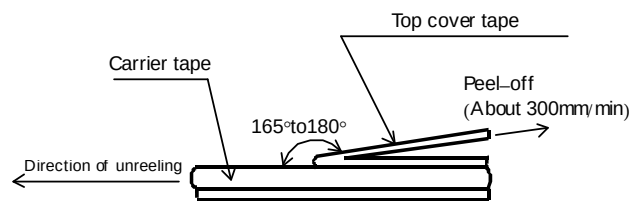


Figure-5

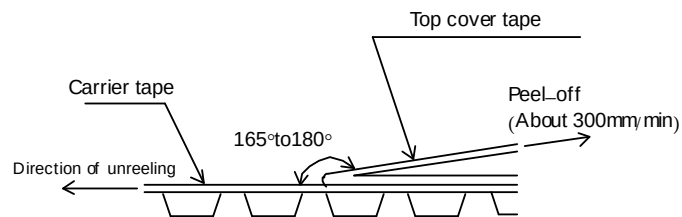


Figure-6

8.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure-7 and Table-7.

Plastic reel (Based on EIAJ ET-7200C)

Unit: mm

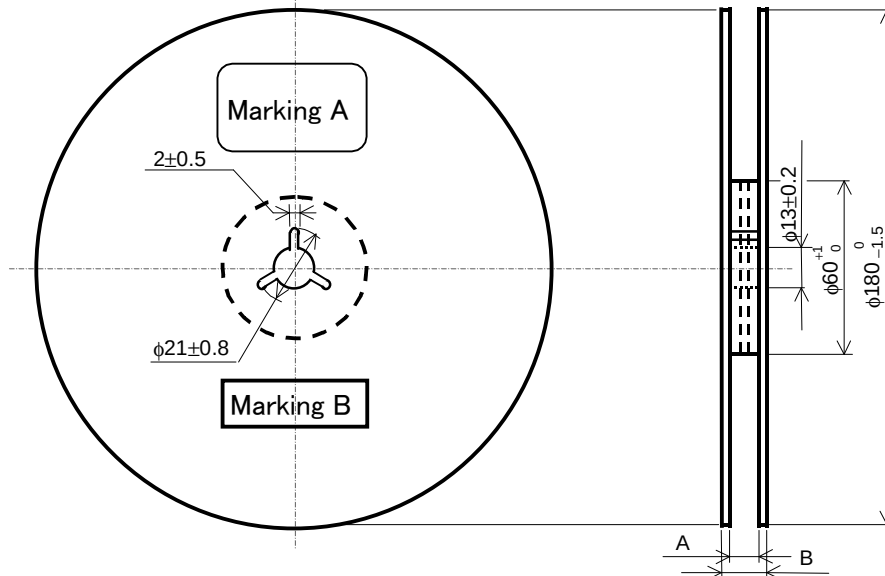


Figure-7

Table-7

Unit: mm

Style	A	B	Note
RPGW16,20,32,35	9 $\begin{smallmatrix} +1.0 \\ 0 \end{smallmatrix}$	11.4±1.0	Injection molding
		13±1.0	Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

8.4 Leader and trailer tape.

(Example)

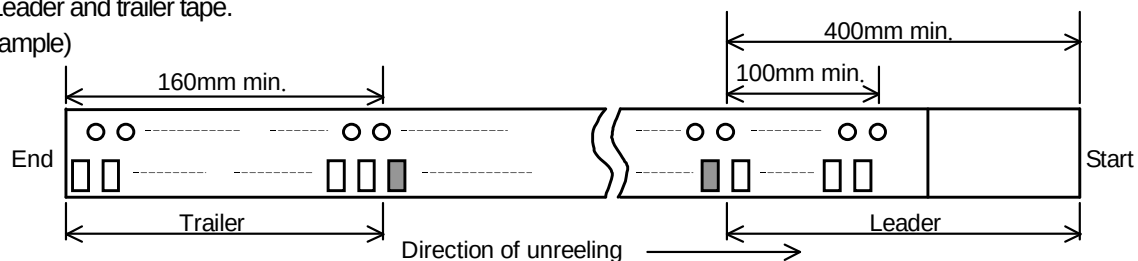


Figure-8

9. Marking on package

The label of a minimum package shall be legibly marked with follows.

9.1 Marking A

(1) Classification

(Style, Temperature coefficient of resistance, Rated resistance, Tolerance on rated resistance, Packaging form)

(2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others

9.2 Marking B (KAMAYA control label)